

H11L1M, H11L2M, H11L3M 6-Pin DIP Optocoupler

Features

- High data rate, 1MHz typical (NRZ)
- Free from latch up and oscillation throughout voltage and temperature ranges.
- Microprocessor compatible drive
- Logic compatible output sinks 16mA at 0.4V maximum
- Guaranteed on/off threshold hysteresis
- Wide supply voltage capability, compatible with all popular logic systems
- Underwriters Laboratory (UL) recognized—file #E90700, Volume 2
- VDE recognized – File#102497 – Add option V (e.g., H11L1VM)

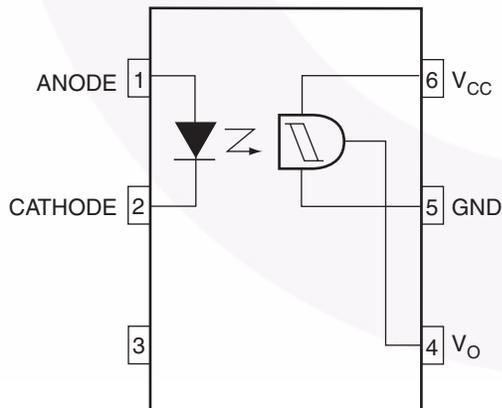
Applications

- Logic to logic isolator
- Programmable current level sensor
- Line receiver—eliminate noise and transient problems
- A.C. to TTL conversion—square wave shaping
- Digital programming of power supplies
- Interfaces computers with peripherals

Description

The H11LXM series has a high speed integrated circuit detector optically coupled to a gallium-arsenide infrared emitting diode. The output incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping. The detector circuit is optimized for simplicity of operation and utilizes an open collector output for maximum application flexibility.

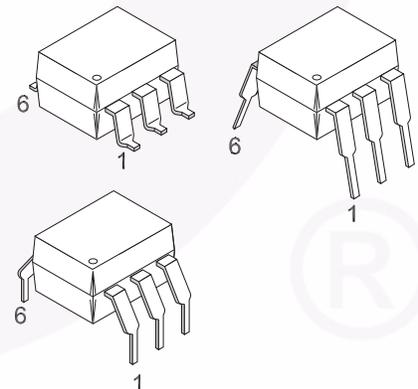
Schematic



Truth Table

Input	Output
H	L
L	H

Package Outlines



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise specified.)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Value	Units
TOTAL DEVICE			
T_{STG}	Storage Temperature	-40 to +150	$^\circ\text{C}$
T_{OPR}	Operating Temperature	-40 to +85	$^\circ\text{C}$
T_{SOL}	Lead Solder Temperature	260 for 10 sec	$^\circ\text{C}$
P_D	Total Device Power Dissipation @ 25°C	250	mW
	Derate Above 25°C	2.94	mW/ $^\circ\text{C}$
EMITTER			
I_F	Continuous Forward Current	60	mA
V_R	Reverse Voltage	6	V
$I_F(pk)$	Forward Current – Peak (1 μs pulse, 300pps)	3.0	A
P_D	LED Power Dissipation 25°C Ambient	120	mW
	Derate Linearly From 25°C	1.41	mW/ $^\circ\text{C}$
DETECTOR			
P_D	Detector Power Dissipation @ 25°C	150	mW
	Derate Linearly from 25°C	2.0	mW/ $^\circ\text{C}$
V_O	V_{45} Allowed Range	0 to 16	V
V_{CC}	V_{65} Allowed Range	3 to 16	V
I_O	I_4 Output Current	50	mA

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)**Individual Component Characteristics**

Symbol	Parameters	Test Conditions	Device	Min.	Typ.	Max.	Units
EMITTER							
V_F	Input Forward Voltage	$I_F = 10\text{mA}$	All		1.2	1.5	V
		$I_F = 0.3\text{mA}$		0.75	1.0		
I_R	Reverse Current	$V_R = 3\text{V}$	All			10	μA
C_J	Capacitance	$V = 0, f = 1.0\text{MHz}$	All			100	pF
DETECTOR							
V_{CC}	Operating Voltage Range		All	3		15	V
$I_{CC(\text{off})}$	Supply Current	$I_F = 0, V_{CC} = 5\text{V}$	All		1.6	5.0	mA
I_{OH}	Output Current, High	$I_F = 0, V_{CC} = V_O = 15\text{V}$	All			100	μA

Transfer Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Typ.	Max.	Units
DC CHARACTERISTICS							
$I_{CC(\text{on})}$	Supply Current	$I_F = 10\text{mA}, V_{CC} = 5\text{V}$	All		1.6	5.0	mA
V_{OL}	Output Voltage, low	$R_L = 270\Omega, V_{CC} = 5\text{V}, I_F = I_{F(\text{on})} \text{ max.}$	All		0.2	0.4	V
$I_{F(\text{on})}$	Turn-On Threshold Current ⁽¹⁾	$R_L = 270\Omega, V_{CC} = 5\text{V}$	H11L1M			1.6	mA
			H11L2M			10.0	
			H11L3M			5.0	
$I_{F(\text{off})}$	Turn-Off Threshold Current	$R_L = 270\Omega, V_{CC} = 5\text{V}$	All	0.3	1.0		mA
$I_{F(\text{off})}/I_{F(\text{on})}$	Hysteresis Ratio	$R_L = 270\Omega, V_{CC} = 5\text{V}$	All	0.50	0.75	0.90	
AC CHARACTERISTICS, Switching Speed							
t_{on}	Turn-On time	$R_L = 270\Omega, V_{CC} = 5\text{V}, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	All		1.0	4	μs
t_f	Fall Time	$R_L = 270\Omega, V_{CC} = 5\text{V}, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	All		0.1		μs
t_{off}	Turn-Off Time	$R_L = 270\Omega, V_{CC} = 5\text{V}, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	All		1.2	4	μs
t_r	Rise time	$R_L = 270\Omega, V_{CC} = 5\text{V}, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	All		0.1		μs
	Data Rate		All		1.0		MHz

Isolation Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	$t = 1 \text{ sec.}$	7500			V_{PEAK}
C_{ISO}	Isolation Capacitance	$V_{I-O} = 0\text{V}, f = 1\text{MHz}$		0.4	0.6	pF
R_{ISO}	Isolation Resistance	$V_{I-O} = \pm 500 \text{ VDC}$	10^{11}			Ω

Note:

- Maximum $I_{F(\text{ON})}$ is the maximum current required to trigger the output. For example, a 1.6mA maximum trigger current would require the LED to be driven at a current greater than 1.6mA to guarantee the device will turn on. A 10% guard band is recommended to account for degradation of the LED over its lifetime. The maximum allowable LED drive current is 60mA.

Typical Performance Curves

Figure 1. Transfer Characteristics

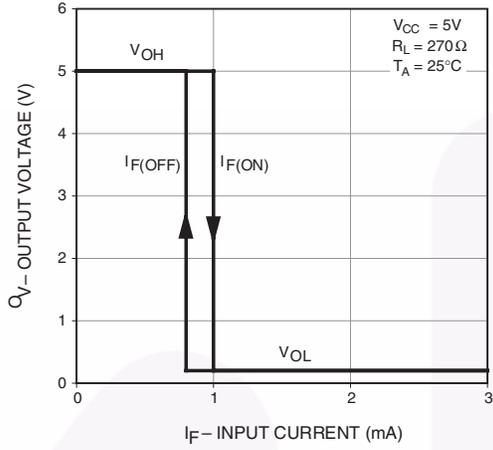


Figure 2. Threshold Current vs. Supply Voltage

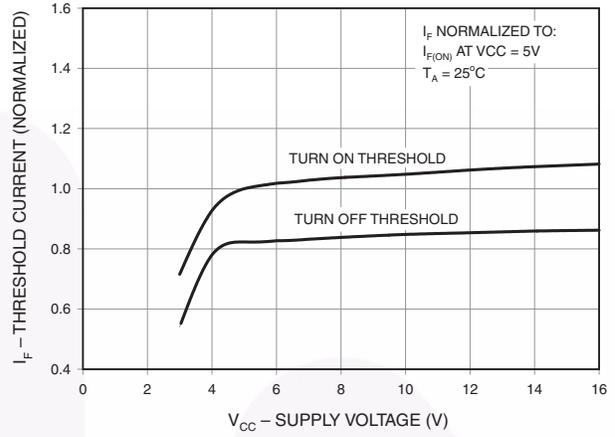


Figure 3. Threshold Current vs. Supply Temperature

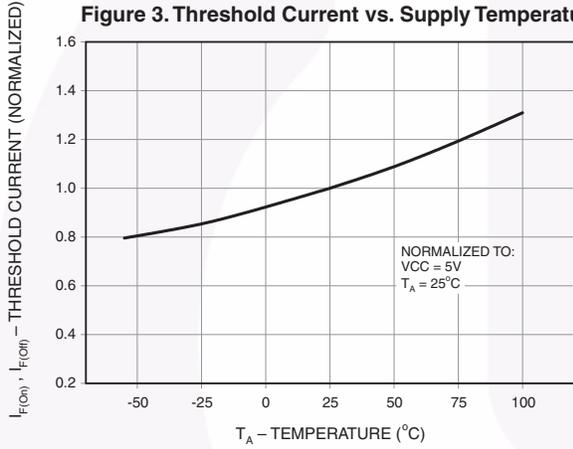


Figure 4. Output Voltage, Low vs. Load Current

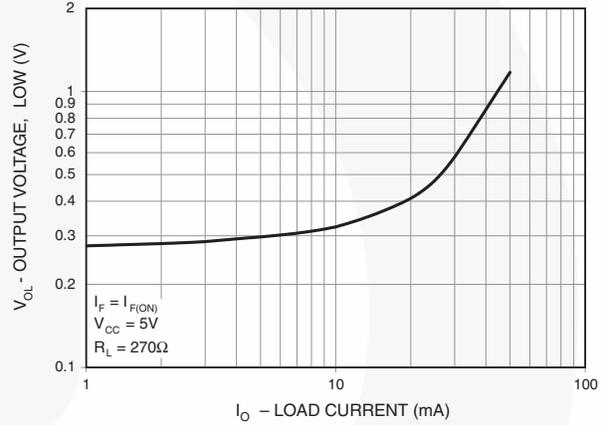


Figure 5. Supply Current vs. Supply Voltage

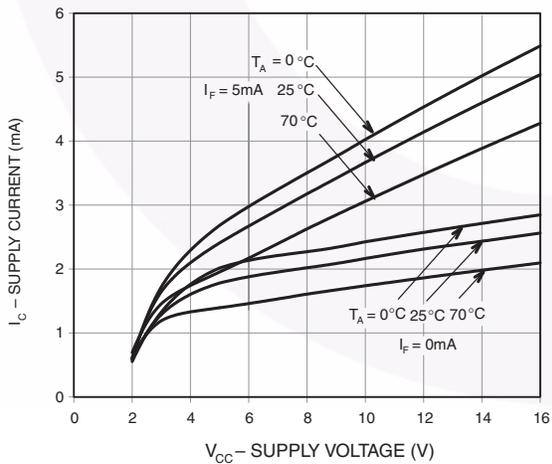
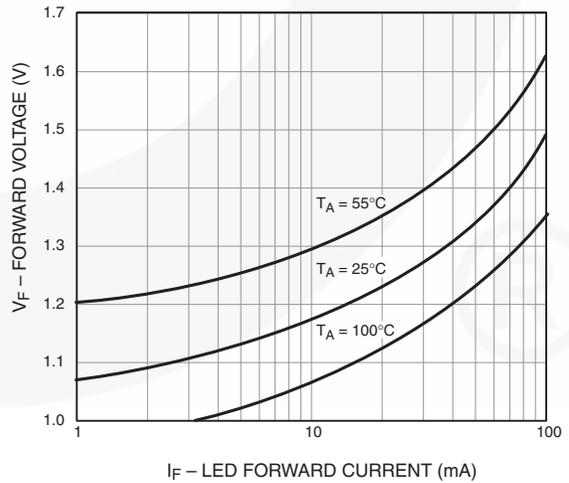


Figure 6. LED Forward Voltage vs. Forward Current



Typical Performance Curves (Continued)

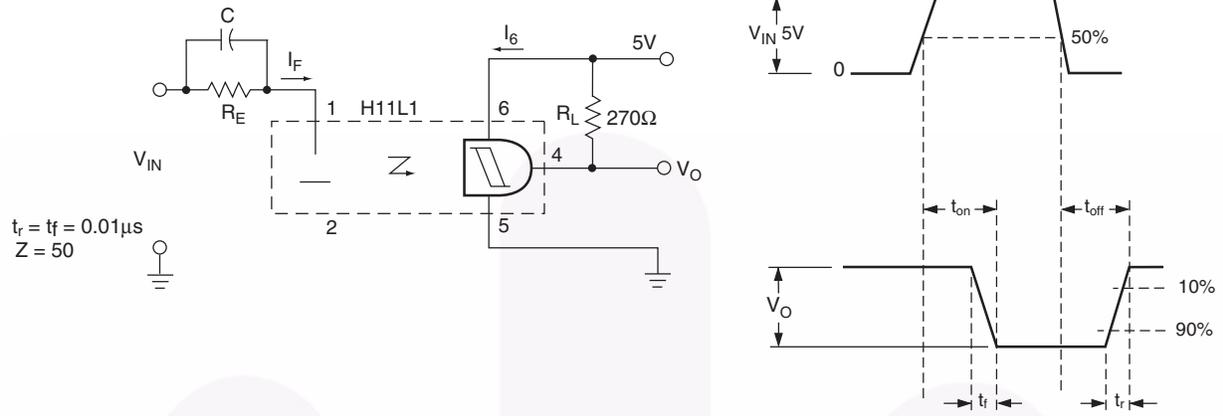
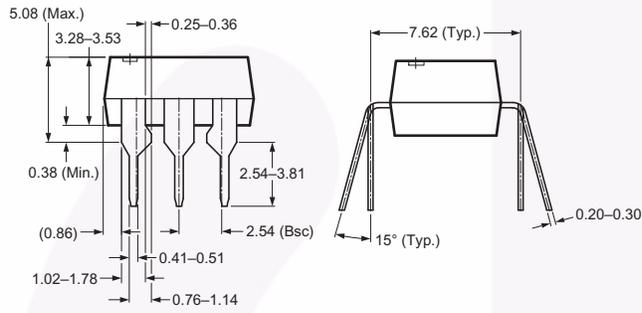
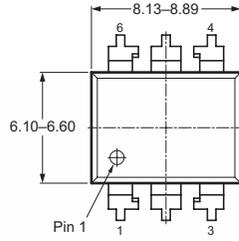


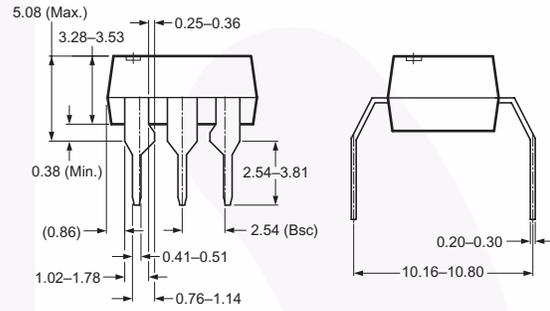
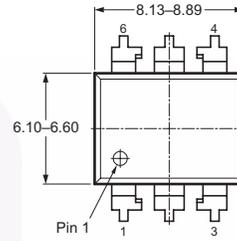
Figure 7. Switching Test Circuit and Waveforms

Package Dimensions

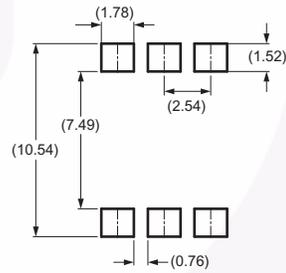
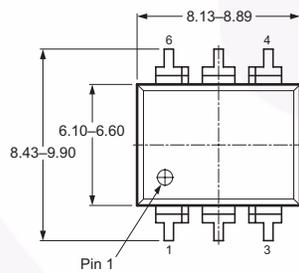
Through Hole



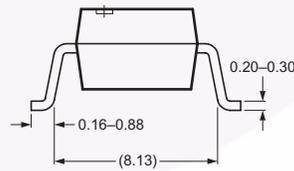
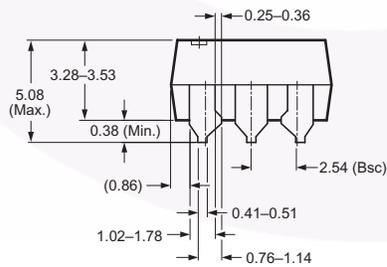
0.4" Lead Spacing



Surface Mount



Recommended Pad Layout

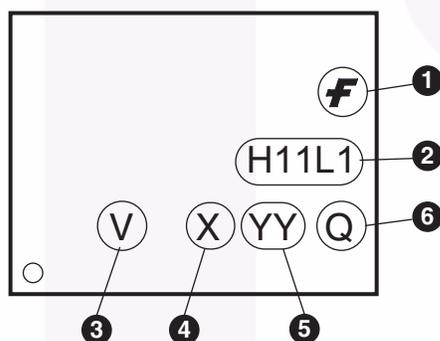


Note:
All dimensions in mm.

Ordering Information

Option	Order Entry Identifier (Example)	Description
No option	H11L1M	Standard Through Hole Device
S	H11L1SM	Surface Mount Lead Bend
SR2	H11L1SR2M	Surface Mount; Tape and Reel
T	H11L1TM	0.4" Lead Spacing
V	H11L1VM	VDE 0884
TV	H11L1TVM	VDE 0884, 0.4" Lead Spacing
SV	H11L1SVM	VDE 0884, Surface Mount
SR2V	H11L1SR2VM	VDE 0884, Surface Mount, Tape and Reel

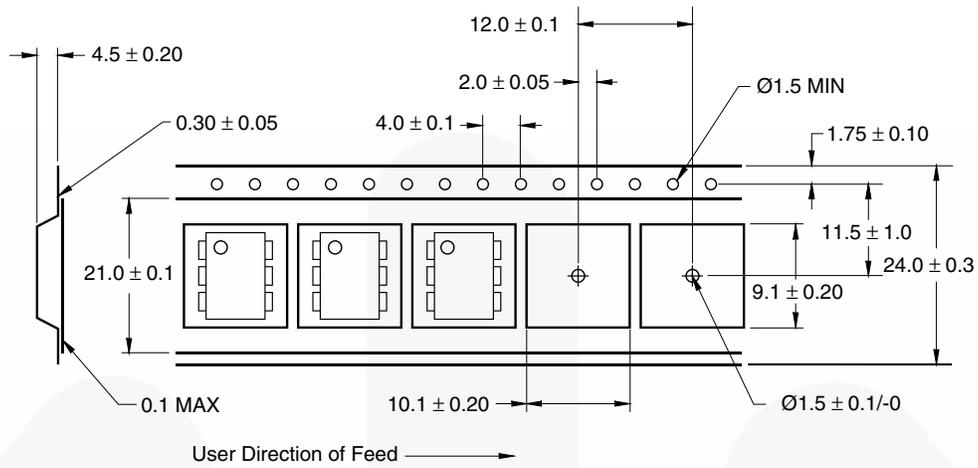
Marking Information



Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

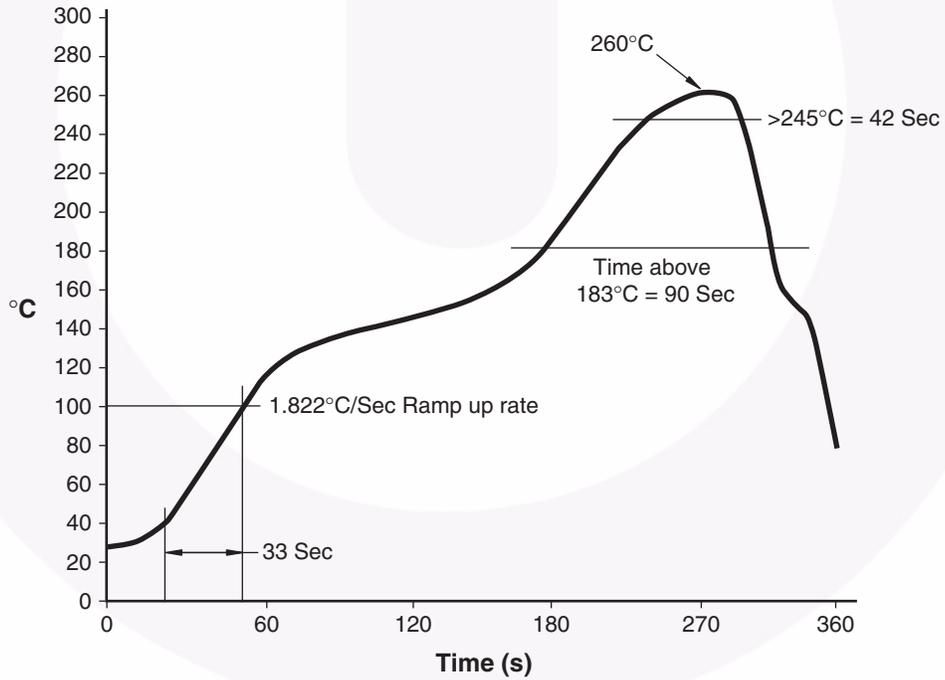
*Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.

Tape Dimensions



Note:
All dimensions are in millimeters.

Reflow Profile





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